INTERNATIONAL CONFERENCE ON TRENDS IN ELECTRONICS & COMMUNICATION (IC-TELCON- 2019)

February 22nd & 23rd, 2019 Friday & Saturday

Registration Form

Name:		
Designation:		
Organisation/Institute:		
Address:		
Email-ID:		
Mobile No.:		
Title of Paper:		
Accomodation Required : Yes/No		
Details of Registration Fee:		
DD/Cheque (Only local) in favour of TELCON		
Payable at Mumbai.		
Category:DD/Cheque No.:		
Amount:Bank:		
Date:		
Place:		
Signature:		
*Note: Paper should be sent to:		
https://easychair.org/conferences/?conf=telcon2019		

Contact us

Conference Registration Information (Registration Fees Payment Details/ Acknowledgements)

> Mrs. Archana Deshpande: +91-9820448939 **Conference Publication Information** Ms. Sujata Alegavi: +91-9819527712

> > **Specific Information**

Mr. Manoj Chavan (SPA): +91-7021637149

Ms. Poorva Waingankar (ED&V): +91-9323906881

Dr. Sangeeta Mishra (CAME): +91-9029082006

Ms. Leena Chakraborty (RA&ES): +91-9930760138

General Information

Ms. Vidya P./Raksha K.: Phone: 67308000/106/107 Time: 9 a.m to 6 p.m Accomodation

Mr. Sunil Khatri: +91-8237296992, Mr. Deepak Singh: +91-8286972263

Communication Saturday ඨ Friday 2019, 1 rends **23**rd nternational Conference on February 22nd

Mishra & Programme Chairperson Principal

Mumbai - Maharashtra, India, PIN 400 101

(If undelivered return to the address above)



Institute with 'A' Grade AICTE-CII Survey rating in Platinum category for

survey on 24th May 2018





International Conference on Trends in Electronics & Communication - 2019



February 22nd & 23rd 2019 Friday & Saturday

Organized by

Department of Electronics & Telecommunication & Electronics Engineering In Association With









A - Block, Thakur Educational Campus, Shyamnarayan Thakur Marg Thakur Village, Kandivali (East), Mumbai - 400 101 Tel.: 022-6730 8000 / 8106 / 8107 Telefax: 022-2846 1890 • Email: tcet@thakureducation.org Website: www.tcetmumbai.in www.thakureducation.org

About the Conference

Modern world increasingly depends on electronic devices to make our life easier. The present day technological and digital transformation is changing the world and is offering challenging opportunities for engineers. Electronics Engineering has a vital position in this revolution as it is the amalgamation of all the state of the art technologies like electronic devices modeling and simulation, VLSI and Nano-technology, Robotics, Automation and Embedded Systems, telecommunication adds the Signal Processing, Antenna & Microwave communication. To discuss and deliberate on such domain specific developments, TCET has successfully held nine international events in a row in association with international journals of repute and in the IT industry with an objective to reach new horizons.

Conference on Trends in Electronics & Communication (TELCON) aims to bring together researchers, engineers, and scholar students to exchange and share their experiences, new ideas, and research results about all aspects in the field of Electronics engineering and communication. TELCON looks to provide a platform to researchers and practitioners from both academia as well as industry to meet and share cutting-edge development in the field and it aims to provide an opportune forum and vibrant platform for Researchers.

Department of Electronics and Telecommunication Engineering & Department of Electronics Engineering of Thakur college of Engineering and Technology, Mumbai takes immense pleasure to invite your contributions for Conference on Trends in Electronics & Communication (TELCON -2019) during February 22nd -23rd, 2019.

Conference Tracks

·Communication, Antenna & Microwave Engineering (CAME)

- Optical Communications & * Networking
- Wireless Communications & Antenna using Meta materials Networking
- Wireless Sensor Networks
- Mobile Networks & Services
- Cognitive Radio Networks
- * RF Circuit Design

- Broadband Antennas & Antenna Measurements
- Ultra Wide Band (UWB) Antennas
- MEMS/NANO Technology for
 - Antennas Wearable, Implanted &
 - **Encapsulated Antennas**
- **Deep Space Communication** Software Defined Radio And related

- ·Signal Processing & Applications (SPA)
- Image and Video Processing
- Audio and Speech Processing
- Multimedia Signal Processing
- Radar & Sonar Signal Processing
- Image and Video Processing
- Biomedical Signal Processing and applications
- Information & Data Processing
- Augmented Reality
- DSP & ADSP Chips
- ** Wavelets

·Electronic Components, Devices and VLSI (EDEV

- Analog/Digital/Mixedsignal Circuits
- Compound Semiconductor & high speed devices
- Power devices & applications
- Sensors, MEMS, & BioMEMS
- Imaging & Visualization Devices
- Devices
- VLSI for DSP
- MMIC & CMOS Circuits
- VLSI testing & relibility

Lab on a Chip & Microfluidic

- Optoelectronics
- **Electronic Displays**

Robotics Automation & Embedded sustems (RA & ES)

- Modeling & Simulation
- Industrial Networks & Automation

Nano Electronics

- Smart City
- Artificial Intelligent systems * & Application
- Mobile Robots & Intelligent * **Autonomous Systems**
- High Performance Computing Systems
- Hardware & software support for real time application
- Internet of Things
- Sensors, Transducer
 - Health Monitoring Devices, Reconfigurable Systems

Publication Details

All selected quality papers will be published in MULTICON- W 2019 proceedings with ISBN & few quality papers will be published in one of the following journal

- 1. Scientific Research Publishing open access journal (Communications & Network [CN], World Journal of Engineering & Technology [WJET]) (Web of Science), CNKI SCHOLAR, COPAC, Worldcat & others
- 2. IOSR-JEN (UGC approved) with indexing in IC Journals & others
- 3. JETIR (UGC approved) with Copernicus International Indexing & others
- 4. IGI Global (International Journal of Electronics, Communications & Measurement Engineering) IET Inspec, ACM Digital Library & others

Note: For more details visit our conference website

Registration Details

Registration Fees (in INR)	On or Before 15/01/2019	After 15/01/2019
	Conference	Conference
Out House	₹4000*	₹5000*
UG, PG & Ph.D.		
Students, Faculty		
& Industry Delegates		
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*Additional Publication Cost to be borne if applicable **Note:** Paper should be sent to:

https://goo.gl/rP2X31

For further details refer conference website: ictelcon.multiconw.co.in

Important Dates

Paper Submission Deadline: 15/12/2018 Paper Selection Notification: 05/01/2019 Registration Deadline: 15/01/2019 Camera Ready Submission Deadline: 20/01/2019

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Dr. B.K. Mishra, Principal

Program Co-Chair

Dr. Deven Shah, Vice-Principal

Technical Chair

Dr. Lochan Jolly, Dean SSW

Convenor

Dr. Vinit Kumar Dongre, Professor, HOD-EXTC

Ioint Convenor

Dr. S C Patil, Associate Professor & Dy HOD-ETRX

Co-convenors

Mr. Sanjeev Ghosh, Associate Professor & Dy HOD-EXTC

Mr. Hemant Kasturiwale. Associate Professor. ETRX

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